# DEW POINT CONTROL PROCEDURE

When wall cladding panels are bonded, the substrate ( the back of the wall cladding panel or the front of the vertical battens) must be prevented from becoming damp due to condensation. Therefore, bonding should not be carried out if the air humidity is too high, the relative humidity of the air should not exceed a value of 90 %.

The table below shows the dew point (is the temperature to which the air must be cooled in order to become saturated (with equal amounts of water vapor and pressure)) depending on ambient temperature and relative humidity. With further cooling, i.e. at a lower temperature, condensation occurs on the surface of the substrate. If the ambient temperature and relative humidity are in the red range, bonding should not take place.

For more accurate values please have a look at LINK

To prevent possible condensation, the substrate temperature should always be 3°C higher than the dew point.

| Temp. (°C) | 50 | 55 | 60 | 65 | 70 | 75 | 80 | 85 | 90 | 95 | 100 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| **50** | 37 | 38 | 40 | 41 | 43 | 44 | 45 | 46 | 47 | 49 | 50 |
| **45** | 32 | 34 | 35 | 37 | 38 | 39 | 41 | 42 | 43 | 44 | 45 |
| **40** | 28 | 29 | 31 | 32 | 34 | 35 | 36 | 37 | 38 | 39 | 40 |
| **35** | 23 | 25 | 26 | 27 | 29 | 30 | 31 | 32 | 33 | 34 | 35 |
| **30** | 19 | 20 | 21 | 23 | 24 | 25 | 26 | 27 | 28 | 29 | 30 |
| **26** | 15 | 16 | 17 | 19 | 20 | 21 | 22 | 23 | 24 | 25 | 26 |
| **25** | 14 | 15 | 16 | 18 | 19 | 20 | 21 | 22 | 23 | 24 | 25 |
| **24** | 13 | 14 | 15 | 17 | 18 | 19 | 20 | 21 | 22 | 23 | 24 |
| **22** | 11 | 12 | 13 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | 22 |
| **20** | 9 | 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 |
| **18** | 7 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 |
| **16** | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 |
| **15** | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 |
| **14** | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 |
| **12** | 2 | 3 | 4 | 6 | 7 | 8 | 9 | 10 | 10 | 11 | 12 |
| **10** | 0 | 1 | 3 | 4 | 5 | 6 | 7 | 7 | 8 | 9 | 10 |
| **8** | -2 | 0 | 1 | 2 | 3 | 4 | 5 | 6 | 6 | 7 | 8 |
| **6** | -3 | -2 | -1 | 0 | 1 | 2 | 3 | 4 | 4 | 5 | 6 |
| **4** | -5 | -3 | -2 | -2 | -1 | 0 | 1 | 1 | 2 | 3 | 4 |
| **2** | -7 | -5 | -4 | -3 | -2 | -1 | 0 | 0 | 1 | 1 | 2 |
| **0** | -8 | -7 | -6 | -5 | -4 | -3 | -2 | -1 | -1 | 0 | 0 |
| **-5** | -13 | -12 | -10 | -10 | -9 | -8 | -7 | -7 | -6 | -6 | -5 |
| **-10** | -18 | -17 | -16 | -15 | -14 | -13 | -12 | -12 | -11 | -11 | -10 |

No dew point, safe for application
Possible dew on materials, be careful during application
High risk of dew, be extra careful during application